

**DATE 17 DEC 2019** 

## NOTES:

- DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
   CONTROLLING DIMENSION: MILLIMETERS.
- DIMESNION b APPLIES TO PLATED
   TERMINAL AND IS MEASURED BETWEEN
- 0.15 AND 0.30 MM FROM TERMINAL.
  4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

		MILLIMETERS		
	DIM	MIN	MAX	
	Α	0.45	0.55	
	<b>A</b> 1	0.00	0.05	
	АЗ	0.15 REF		
1	b	0.15	0.25	
J	D	3.00 BSC		
	D2	2.40	2.60	
J	E	3.00 BSC		
ı	E2	1.70	1.80	
ı	Φ	0.40 BSC		
	K	0.15		
	L	0.30	0.50	

## GENERIC MARKING DIAGRAM



xxxxx = Specific Device Code

= Assembly Location

L = Wafer Lot

/ = Year

W = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present.

## SCALE 2:1 -AB D PIN 1 REFERENCE Ε ○ 0.15 C 0.15 C **TOP VIEW** // 0.10 C 12X □ 0.08 C (A3) SEATING SIDE VIEW е 12X L e/2 12X **K**

## **SOLDERING FOOTPRINT\***

- 12X **b** 

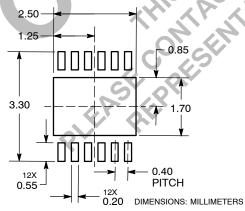
Ф

0.10 C A B

0.05

C (NOTE 3)

**BOTTOM VIEW** 



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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